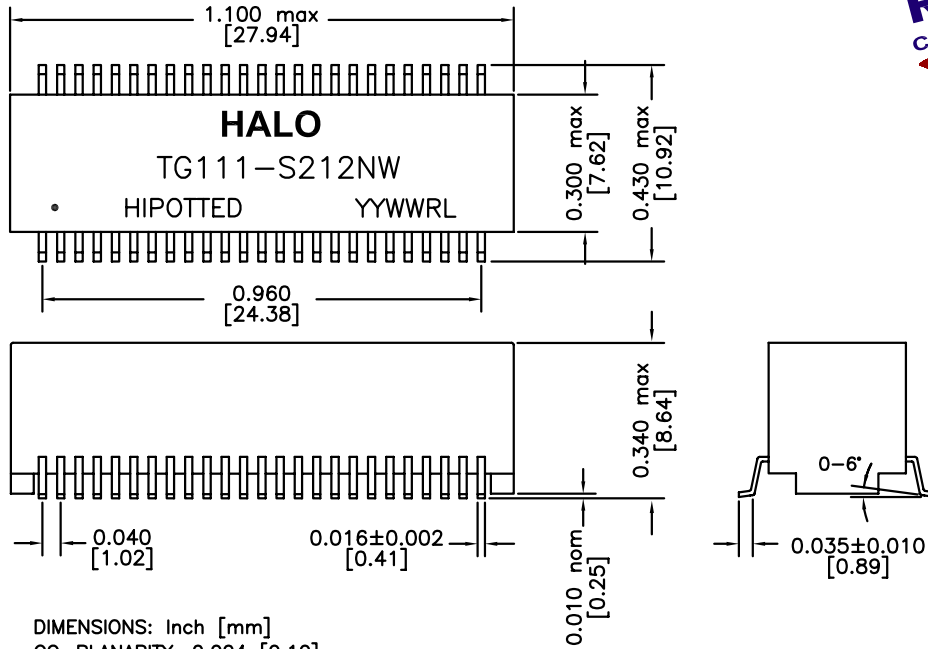


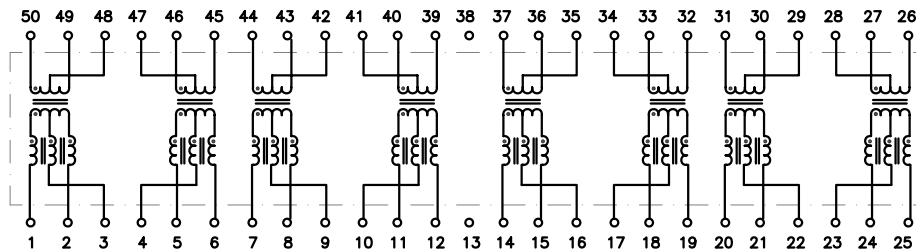


**PART NO. : TG111-S212NWRL**

50PIN 0.040" LEAD PITCH SMT PACKAGE  
 DESIGNED FOR DUAL-PORT GIGABIT, IEEE802.3ab OR  
 FOUR-PORT FAST ETHERNET, IEEE802.3u APPLICATIONS  
 COMPLIANT WITH IEEE802.3af REQUIREMENTS WITH  
 350mA CURRENT CARRYING CAPACITY FOR PoE  
 RoHS COMPLIANT  
 COMPATIBLE TO LEAD-FREE SOLDERING PROCESS  
 CONDITION PER IPC/JEDEC J-STD-020C  
 UL/EN60950 AND DEMKO RECOGNIZED  
 OPERATING TEMPERATURE 0/70°C



DIMENSIONS: Inch [mm]  
 CO-PLANARITY: 0.004 [0.10]  
 TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



**ELECTRICAL SPECIFICATIONS @ 25° C**

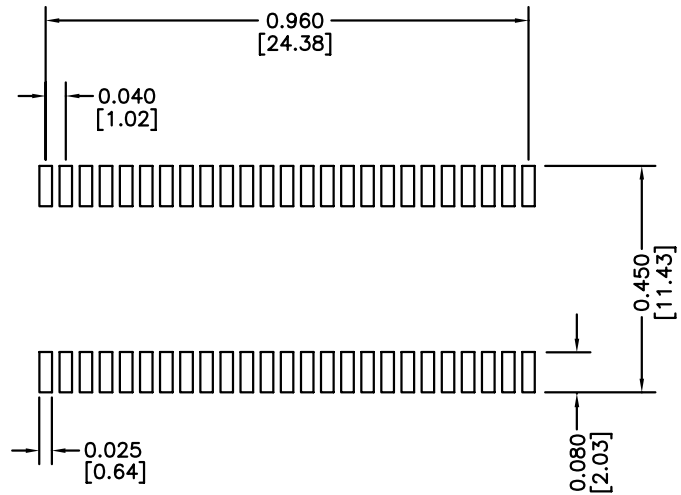
URNS RATIO	1CT:1CT±2%
OCL (100KHz,0.1Vrms,8mADC)	350µH min
INSERTION LOSS 1-100MHz	-1.1dB max
RETURN LOSS 1-40MHz	-18dB min
60MHz	-14dB min
80MHz	-12dB min
100MHz	-10dB min
CMR 1-100MHz	-40dB typ
CROSSTALK 1-30MHz	-50dB typ
60MHz	-45dB typ
100MHz	-40dB typ
ISOLATION	1,500Vrms



**HALO/PBL**

CALIFORNIA, USA  
 KOWLOON, HONG KONG  
 SINGAPORE

TITLE ISOLATION MODULE FOR FAST/GIGABIT ETHERNET PART NO. TG111-S212NWRL SCALE NONE PAGE 1 OF 2	SIGNATURES	DATE	REV.	DESC.	DATE
	DRAWN PETER LU	11/8/05	A	FIRST ISSUE	11/8/05
	CHECKED LEI KEONG	3/20/08	B	PROD. RELEASE	12/21/06
	APPROVED PETER LU	3/20/08	C	REV. TOE LENGTH TOL.	3/20/08
FILE S212NWRL.DWG					



RECOMMENDED SOLDER PAD DIMENSIONS  
 DIMENSIONS: Inch [mm]

**HALO/PBL**

CALIFORNIA, USA  
 KOWLOON, HONG KONG  
 SINGAPORE

TITLE	ISOLATION MODULE		SIGNATURES		DATE	REV.	DESC.	DATE	
FOR	FAST/GIGABIT ETHERNET		DRAWN	PETER LU	11/8/05	A	FIRST ISSUE	11/8/05	
PART NO.	TG111-S212NWRL		CHECKED	LEI KEONG	3/20/08	B	PROD. RELEASE	12/21/06	
SCALE	NONE	PAGE	2 OF 2	APPROVED	PETER LU	3/20/08	C	REV. TOE LENGTH TOL.	3/20/08
				FILE	S212NWRL.DWG				